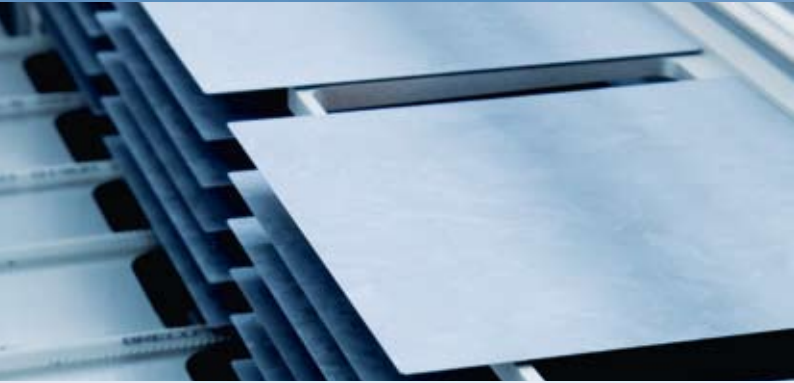


SOLAR

VarioLink

R|E|N|A|.



Direct connection between inline systems

VarioLink is the ideal connection between multi-lane inline systems. The modular system allows the integration of a flipper unit, a wafer breakage control or a multi-lane buffer system.

Areas of application

- Direct transfer between two inline systems
- Emergency buffering of processing system content
- Flipping of cells

Features and benefits

- Optimised compatibility to all RENA tools
 - Modular design for individual configuration
 - Easy to maintain
 - High throughput thanks to continuous wafer transport
 - Low cost of ownership
 - Integrated multi-lane FiFo buffer with a capacity of 100 wafers/lane
 - Lowest breakage rate
- Optional:
- Connection to MES





- FiFo buffer
- Flipper



Alignment unit X-Y-φ



VarioLink

Technical Data VarioLink

Process moduls

optional

- FiFo buffer
- Flipper
- Alignment X-Y-φ
- Breakage discharge

Dimensions

Depending on module combination
min. 1600 x 2150 x 2350 mm (length x width x height)

Wafer s ize

125 and 156 mm

Optional

210 mm

Wafer thickness

> 160 μm

Breakage rate

< 0.05 %

Throughput

max. 3600 wafers/h netto

Uptime

> 98 %

Media consumption

- Compressed air
- Electricity

approx. 10 - 50 l/h

200 - 400 V AC + 5 % 3Ph+N+PE 50 Hz < 32 A